

## Product Summary

BV <sub>DSS</sub>	R <sub>DS(ON)</sub>	I <sub>D</sub> T <sub>A</sub> = +25°C
100V	65mΩ @ V <sub>GS</sub> = 10V	4A
	105mΩ @ V <sub>GS</sub> = 4.5V	3A

## Description

This N-channel MOSFET provides users with a competitive specification, offering efficient power-handling capability, high impedance, and is free from thermal runaway and thermally induced secondary breakdown.

## Applications

- Load Switching
- Uninterrupted Power Supply

## Features and Benefits

- Low Gate Drive
- Low Input Capacitance
- Fast Switching Speed
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please [contact us](#) or your local Diodes representative. <https://www.diodes.com/quality/product-definitions/>**

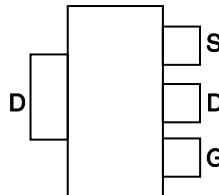
## Mechanical Data

- Case: SOT223
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals Connections: See Diagram Below
- Terminals: Finish - Matte Tin Annealed over Copper Lead-Frame. Solderable per MIL-STD-202, Method 208 <sup>Ⓔ3</sup>
- Weight: 0.112 grams (Approximate)

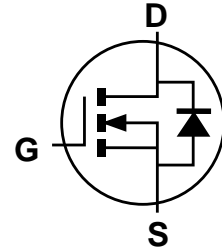
SOT223



Top View



Pin Out - Top View



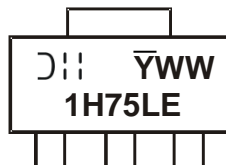
Equivalent Circuit

## Ordering Information (Note 4)

Part Number	Case	Packaging
DMT10H075LE-13	SOT223	2,500 / Tape & Reel

- Notes:
1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
  2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

## Marking Information



Ⓜ = Manufacturer's Marking  
 1H75LE = Marking Code  
 YWW = Date Code Marking  
 Y or  $\bar{Y}$  = Year (ex: 1 = 2121)  
 WW = Week (01 to 53)

**Maximum Ratings** (@  $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Drain-Source Voltage	$V_{DSS}$	100	V
Gate-Source Voltage	$V_{GSS}$	$\pm 20$	V
Continuous Drain Current (Note 6) $V_{GS} = 10\text{V}$	$T_A = +25^\circ\text{C}$	$I_D$	4 A
	$T_A = +70^\circ\text{C}$	$I_D$	3 A
Pulsed Drain Current (10 $\mu\text{s}$ Pulse, Duty Cycle = 1%) (Note 5)	$I_{DM}$	28	A
Maximum Body Diode Continuous Current (Note 6)	$I_S$	12	A
Avalanche Energy (Note 7) $L = 0.1\text{mH}$	$E_{AS}$	6	mJ
Avalanche Current (Note 7) $L = 0.1\text{mH}$	$I_{AS}$	1.8	A

**Thermal Characteristics** (@  $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	$P_D$	2.4	W
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	51	$^\circ\text{C/W}$
Thermal Resistance, Junction to Case	$R_{\theta JC}$	9	$^\circ\text{C/W}$
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150	$^\circ\text{C}$

**Electrical Characteristics** (@  $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS (Note 6)</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	100	—	—	V	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$
Zero Gate Voltage Drain Current	$I_{DSS}$	—	—	1	$\mu\text{A}$	$V_{DS} = 80\text{V}, V_{GS} = 0\text{V}$
Gate-Source Leakage	$I_{GSS}$	—	—	$\pm 100$	nA	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$
<b>ON CHARACTERISTICS (Note 6)</b>						
Gate Threshold Voltage	$V_{GS(TH)}$	1.0	—	3.0	V	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$
Static Drain-Source On-Resistance	$R_{DS(ON)}$	—	43	65	m $\Omega$	$V_{GS} = 10\text{V}, I_D = 4\text{A}$
		—	63	105	m $\Omega$	$V_{GS} = 4.5\text{V}, I_D = 4\text{A}$
Diode Forward Voltage	$V_{SD}$	—	0.8	1.0	V	$V_{GS} = 0\text{V}, I_S = 1\text{A}$
<b>DYNAMIC CHARACTERISTICS (Note 7)</b>						
Input Capacitance	$C_{ISS}$	—	228	—	pF	$V_{DS} = 50\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$
Output Capacitance	$C_{OSS}$	—	89.3	—	pF	
Reverse Transfer Capacitance	$C_{RSS}$	—	2.5	—	pF	
Gate Resistance	$R_g$	—	8.2	—	$\Omega$	$V_{DS} = 0\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$
Total Gate Charge ( $V_{GS} = 4.5\text{V}$ )	$Q_g$	—	2.5	—	nC	$V_{DS} = 50\text{V}, I_D = 4.5\text{A}$
Total Gate Charge ( $V_{GS} = 10\text{V}$ )	$Q_g$	—	4.5	—	nC	
Gate-Source Charge	$Q_{gs}$	—	0.6	—	nC	
Gate-Drain Charge	$Q_{gd}$	—	1.3	—	nC	
Turn-On Delay Time	$t_{D(ON)}$	—	3.0	—	ns	$V_{DS} = 50\text{V}, R_L = 11\Omega$ $V_{GS} = 10\text{V}, R_{GEN} = 3\Omega$
Turn-On Rise Time	$t_r$	—	3.1	—	ns	
Turn-Off Delay Time	$t_{D(OFF)}$	—	12.3	—	ns	
Turn-Off Fall Time	$t_f$	—	4.3	—	ns	
Reverse Recovery Time	$t_{RR}$	—	22.9	—	ns	$I_F = 4.5\text{A}, di/dt = 300\text{A}/\mu\text{s}$
Reverse Recovery Charge	$Q_{RR}$	—	45.2	—	nC	

- Notes:
- Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper pad layout.
  - Short duration pulse test used to minimize self-heating effect.
  - Guaranteed by design. Not subject to production testing.

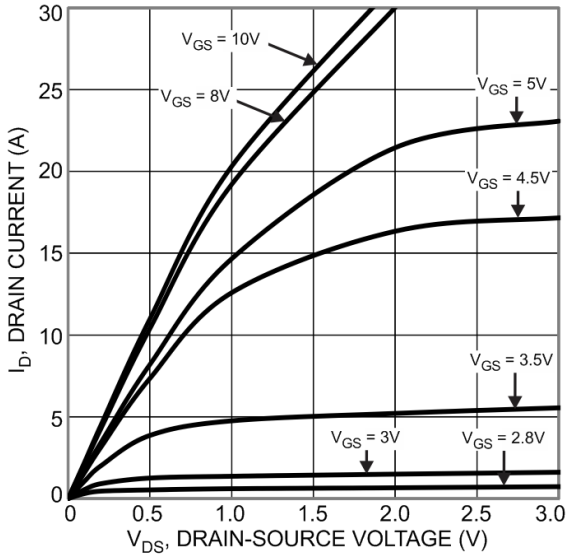


Fig. 1 Typical Output Characteristic

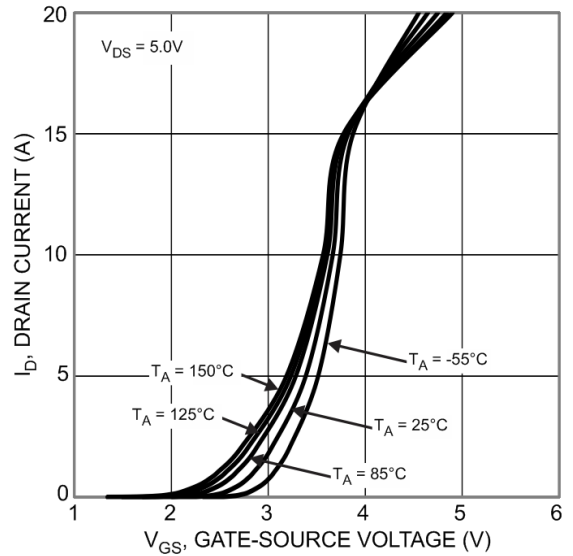


Fig. 2 Typical Transfer Characteristics

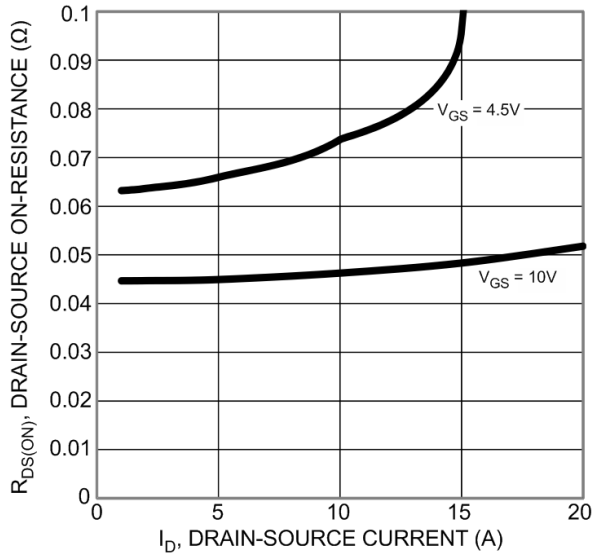


Fig. 3 Typical On-Resistance vs Drain Current and Gate Voltage

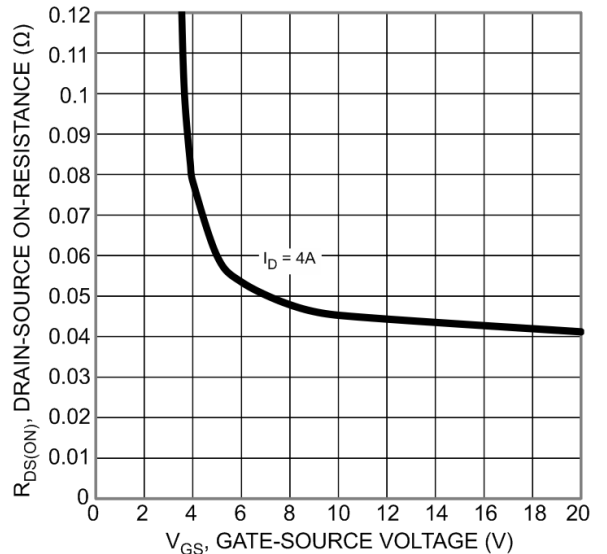


Fig. 4 Typical Transfer Characteristic

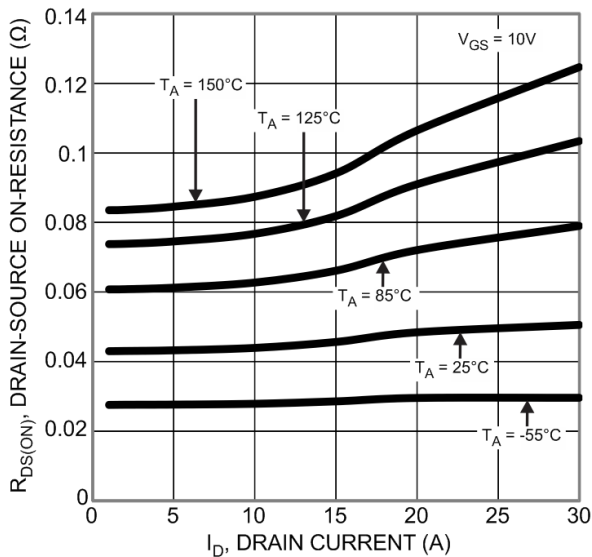


Fig. 5 Typical On-Resistance vs Drain Current and Junction Temperature

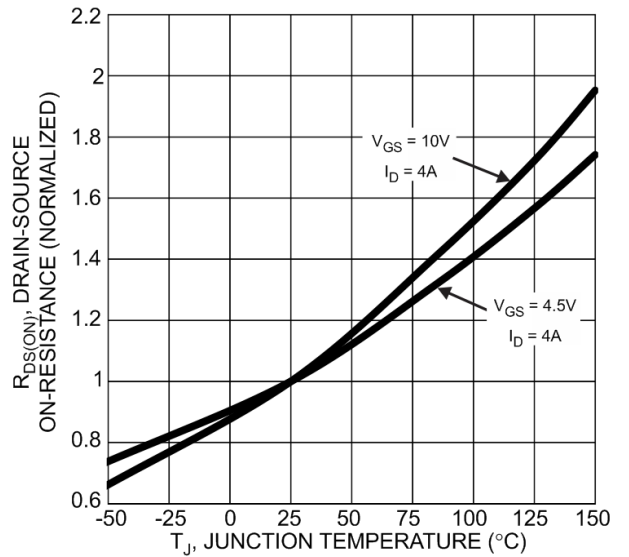


Fig. 6 On-Resistance Variation with Junction Temperature

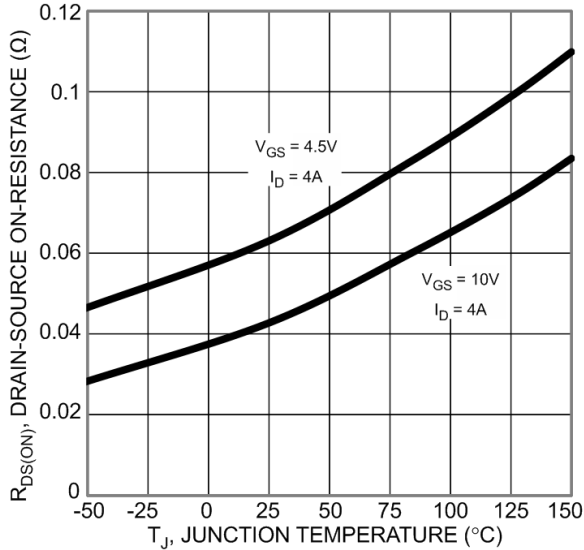


Fig. 7 On-Resistance Variation with Junction Temperature

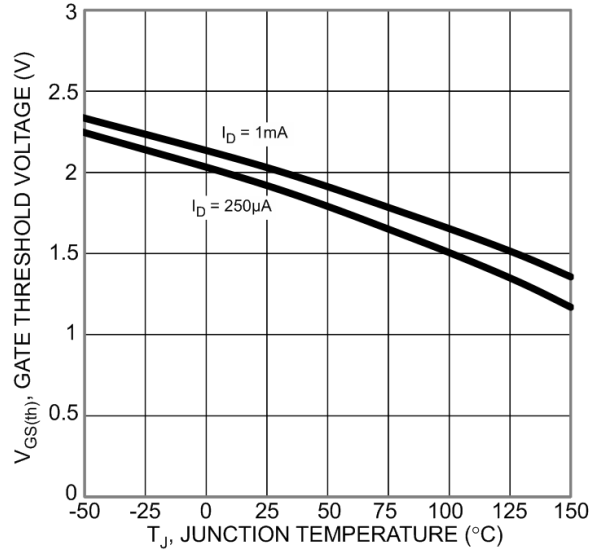


Fig. 8 Gate Threshold Variation vs Junction Temperature

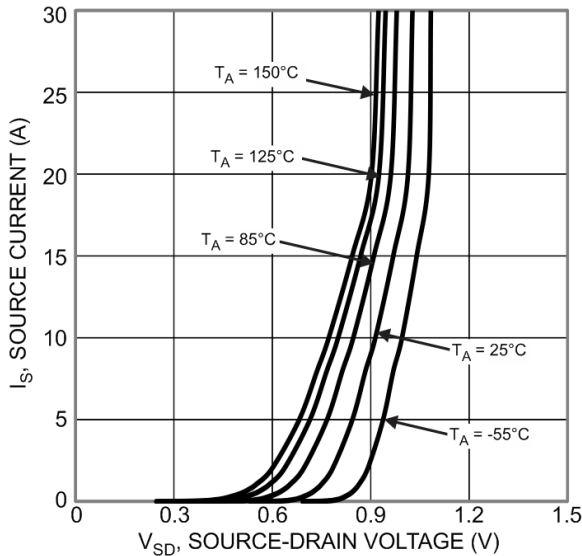


Fig. 9 Diode Forward Voltage vs Current

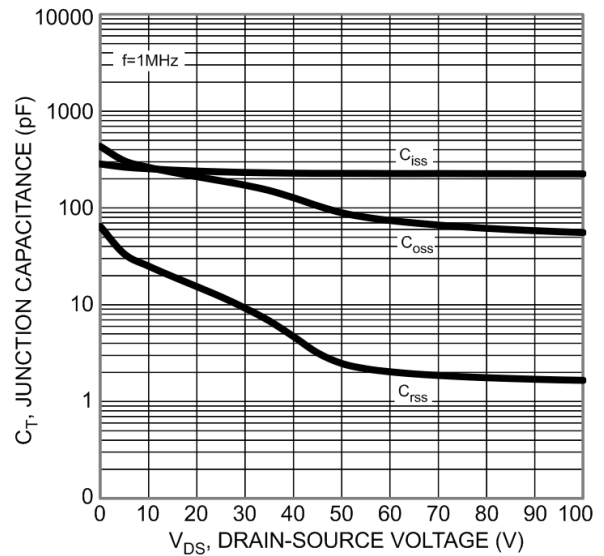


Fig. 10 Typical Junction Capacitance

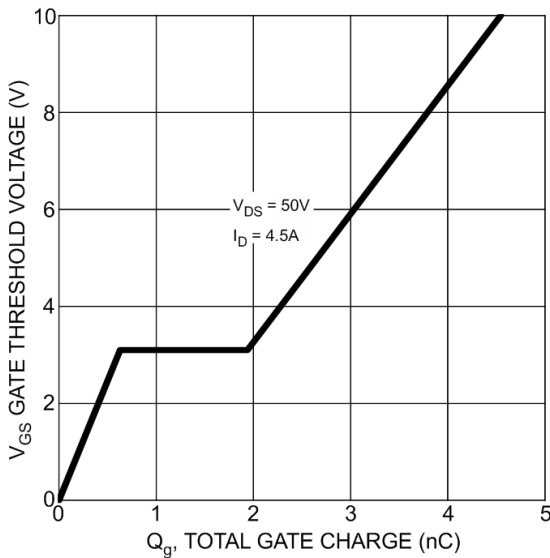


Fig. 11 Gate Charge

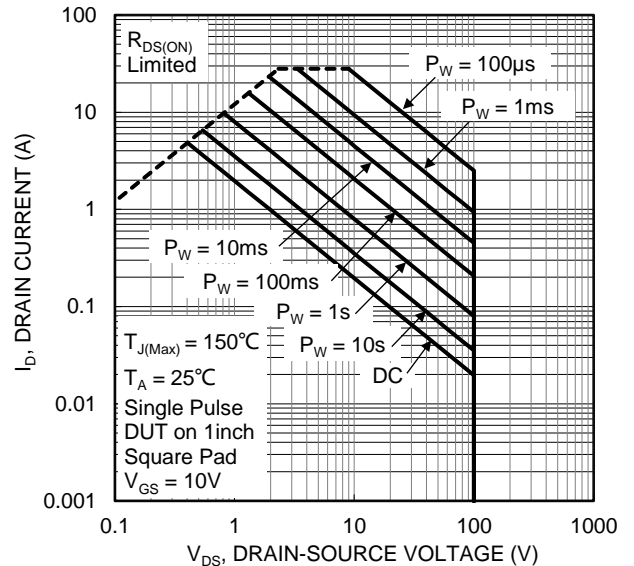


Figure 12. SOA, Safe Operation Area

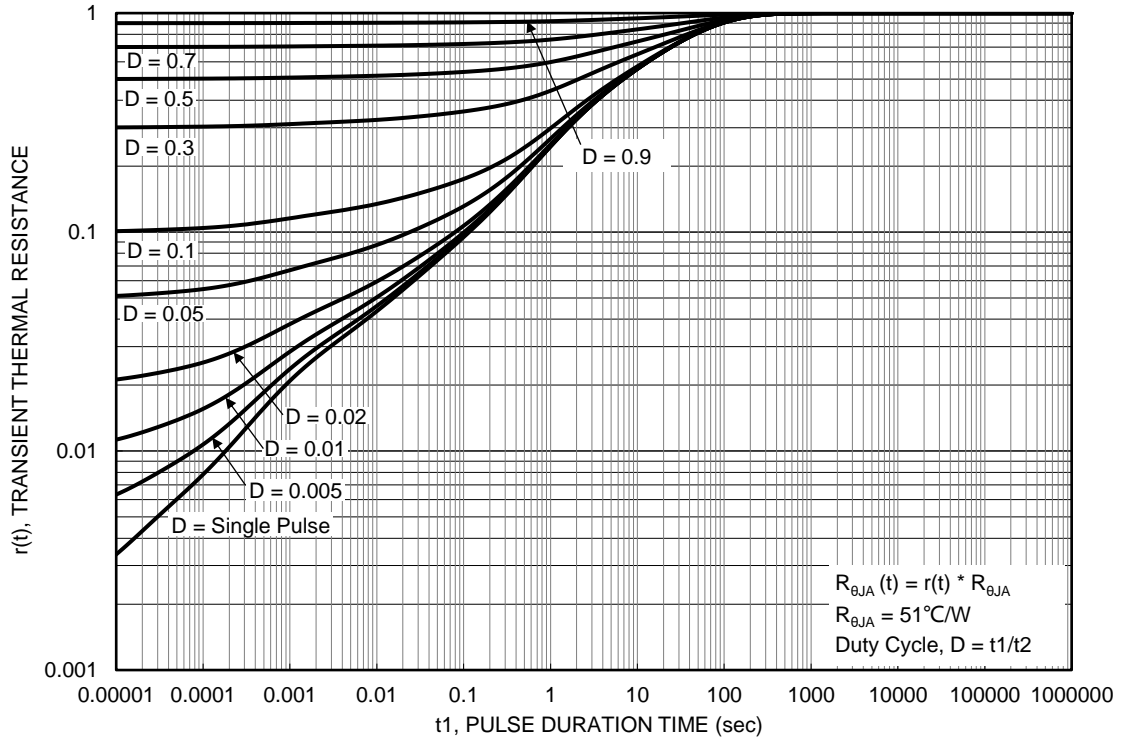
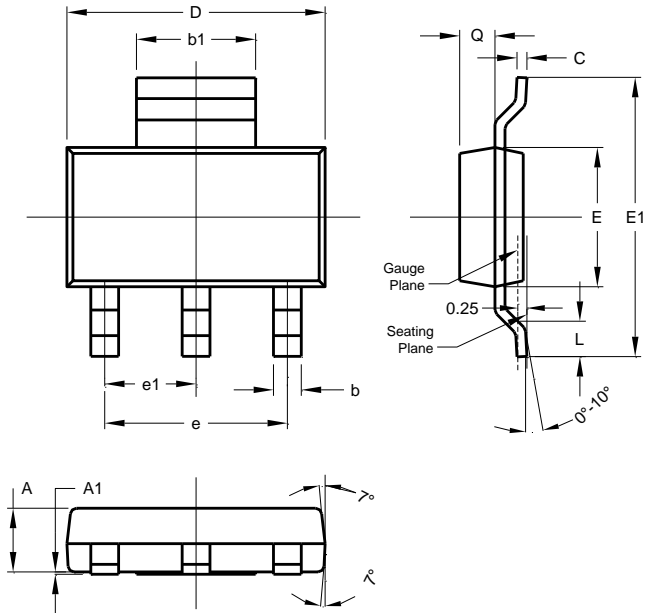


Figure 13. Transient Thermal Resistance

**Package Outline Dimensions**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**SOT223**

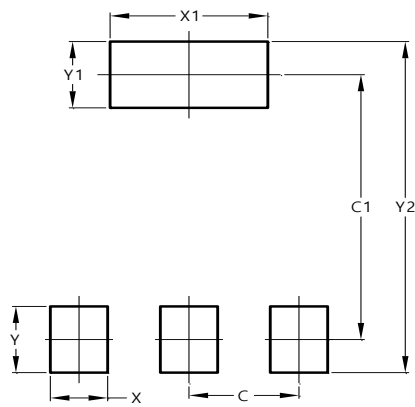


SOT223			
Dim	Min	Max	Typ
A	1.55	1.65	1.60
A1	0.010	0.15	0.05
b	0.60	0.80	0.70
b1	2.90	3.10	3.00
C	0.20	0.30	0.25
D	6.45	6.55	6.50
E	3.45	3.55	3.50
E1	6.90	7.10	7.00
e	-	-	4.60
e1	-	-	2.30
L	0.85	1.05	0.95
Q	0.84	0.94	0.89
<b>All Dimensions in mm</b>			

**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**SOT223**



Dimensions	Value (in mm)
C	2.30
C1	6.40
X	1.20
X1	3.30
Y	1.60
Y1	1.60
Y2	8.00

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